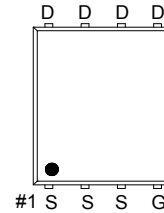
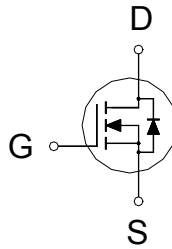




**PRODUCT SUMMARY**

$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$
30V	9mΩ	43A



G. GATE  
D. DRAIN  
S. SOURCE

**ABSOLUTE MAXIMUM RATINGS ( $T_A = 25\text{ °C}$  Unless Otherwise Noted)**

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		$V_{DS}$	30	V
Gate-Source Voltage		$V_{GS}$	±20	V
Continuous Drain Current	$T_C = 25\text{ °C}$	$I_D$	43	A
	$T_C = 100\text{ °C}$		27	
Pulsed Drain Current <sup>1</sup>		$I_{DM}$	120	
Continuous Drain Current	$T_A = 25\text{ °C}$	$I_D$	11	
	$T_A = 70\text{ °C}$		9.3	
Avalanche Current		$I_{AS}$	27	
Avalanche Energy	$L = 0.1\text{mH}$	$E_{AS}$	36	mJ
Power Dissipation	$T_C = 25\text{ °C}$	$P_D$	31	W
	$T_C = 100\text{ °C}$		20	
Power Dissipation	$T_A = 25\text{ °C}$	$P_D$	2.1	W
	$T_A = 70\text{ °C}$		1.4	
Operating Junction & Storage Temperature Range		$T_j, T_{stg}$	-55 to 150	°C

**THERMAL RESISTANCE RATINGS**

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient <sup>2</sup>	$R_{\theta JA}$		57	°C / W
Junction-to-Case	$R_{\theta JC}$		4	

<sup>1</sup>Pulse width limited by maximum junction temperature.

<sup>2</sup>The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25\text{ °C}$ .

**ELECTRICAL CHARACTERISTICS ( $T_J = 25\text{ °C}$ , Unless Otherwise Noted)**

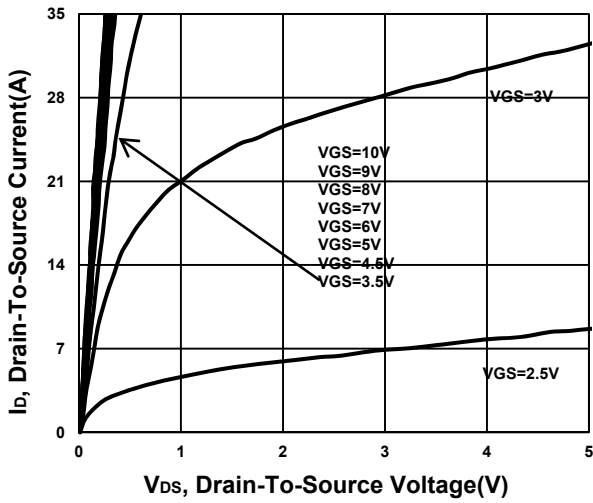
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.3	1.5	3	

Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$			$\pm 100$	nA	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 24V, V_{GS} = 0V$			1	$\mu A$	
		$V_{DS} = 20V, V_{GS} = 0V, T_J = 55^\circ C$			10		
Drain-Source On-State Resistance <sup>1</sup>	$R_{DS(ON)}$	$V_{GS} = 4.5V, I_D = 15A$		9.4	12	m $\Omega$	
		$V_{GS} = 10V, I_D = 20A$		6.8	9		
Forward Transconductance <sup>1</sup>	$g_{fs}$	$V_{DS} = 5V, I_D = 20A$		60		S	
<b>DYNAMIC</b>							
Input Capacitance	$C_{iss}$	$V_{GS} = 0V, V_{DS} = 15V, f = 1MHz$		638		$\mu F$	
Output Capacitance	$C_{oss}$			130			
Reverse Transfer Capacitance	$C_{rss}$			77			
Gate Resistance	$R_g$	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$		2.5		$\Omega$	
Total Gate Charge <sup>2</sup>	$Q_g$	$V_{GS} = 10V$	$V_{DS} = 15V, V_{GS} = 10V, I_D = 20A$		14.5	nC	
		$V_{GS} = 4.5V$			8		
Gate-Source Charge <sup>2</sup>	$Q_{gs}$			2			
Gate-Drain Charge <sup>2</sup>	$Q_{gd}$			4			
Turn-On Delay Time <sup>2</sup>	$t_{d(on)}$	$V_{DS} = 15V, I_D \cong 20A, V_{GS} = 10V, R_{GEN} = 6\Omega$			18		nS
Rise Time <sup>2</sup>	$t_r$				15		
Turn-Off Delay Time <sup>2</sup>	$t_{d(off)}$			34			
Fall Time <sup>2</sup>	$t_f$			16			
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (<math>T_J = 25^\circ C</math>)</b>							
Continuous Current	$I_S$				43	A	
Forward Voltage <sup>1</sup>	$V_{SD}$	$I_F = 20A, V_{GS} = 0V$			1.2	V	
Reverse Recovery Time	$t_{rr}$	$I_F = 20A, di_F/dt = 100A / \mu S$		14		nS	
Reverse Recovery Charge	$Q_{rr}$			5		nC	

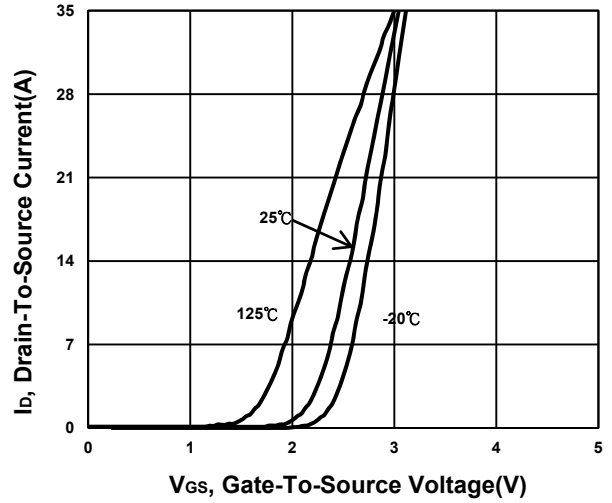
<sup>1</sup>Pulse test : Pulse Width  $\leq 300 \mu sec$ , Duty Cycle  $\leq 2\%$ .

<sup>2</sup>Independent of operating temperature.

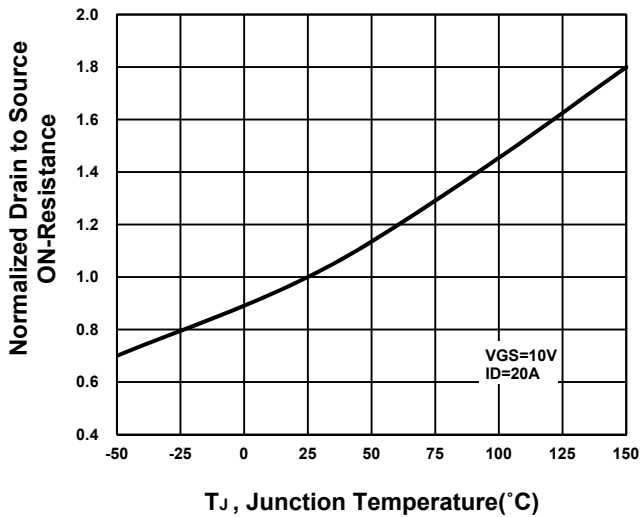
**Output Characteristics**



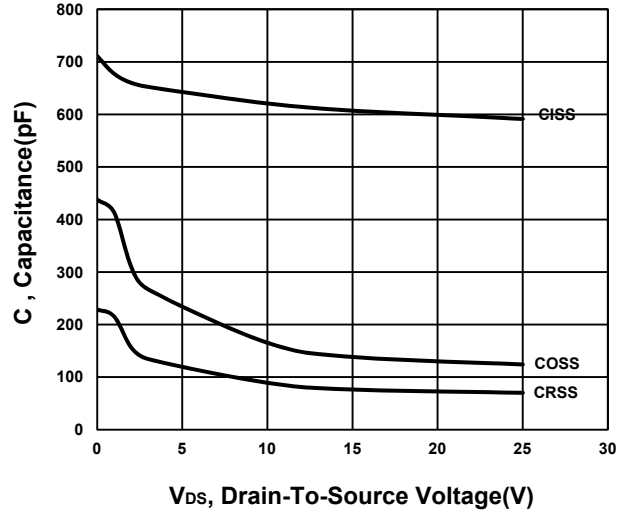
**Transfer Characteristics**



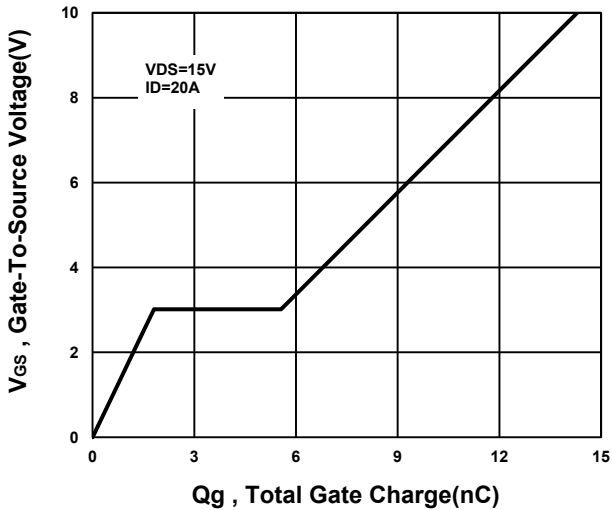
**On-Resistance VS Temperature**



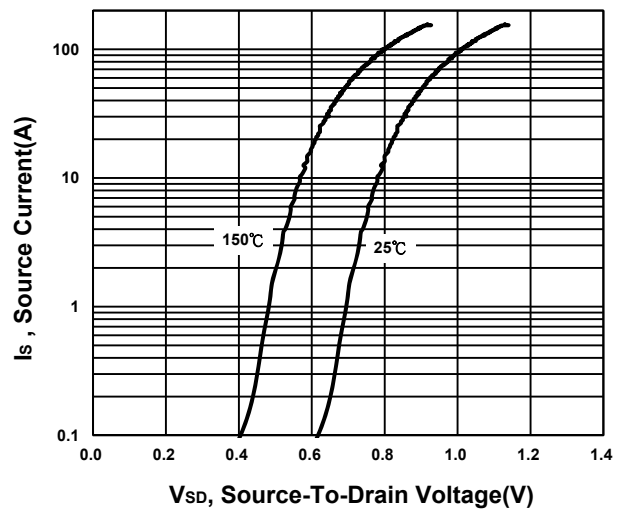
**Capacitance Characteristic**



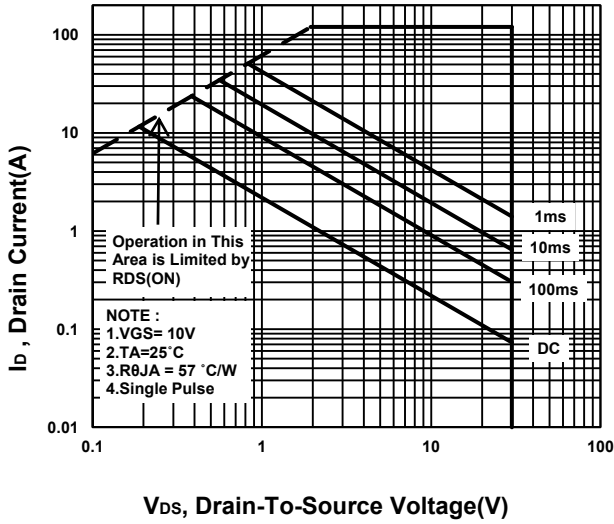
**Gate charge Characteristics**



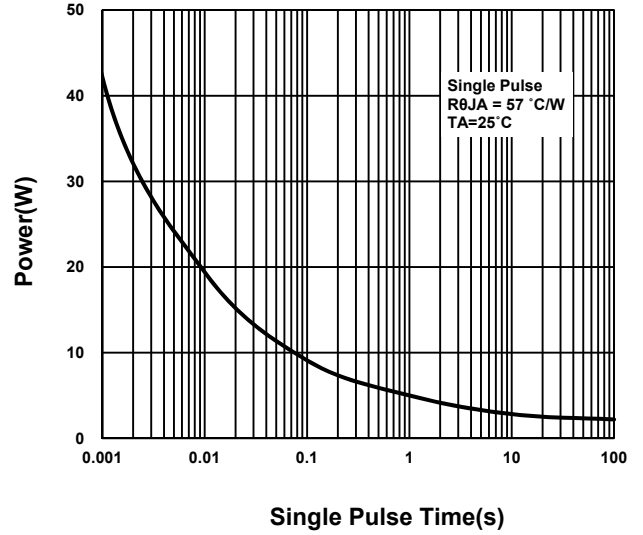
**Source-Drain Diode Forward Voltage**



**Safe Operating Area**



**Single Pulse Maximum Power Dissipation**



**Transient Thermal Response Curve**

